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Final Product/Process Change Notification Document #:FPCN24342X Issue Date:21 Dec 2021

Title of Change:	Changing wire bond from	Changing wire bond from Au to Pd-coated Cu for JFETs assembled in SOT-23.		
Proposed First Ship date:	16 Apr 2022 or earlier	16 Apr 2022 or earlier if approved by customer		
Contact Information:	Contact your local ons	Contact your local onsemi Sales Office or Andy.Tao@onsemi.com		
PCN Samples Contact:	Sample requests are to Initial PCN or Final PCN Samples delivery timin	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.		
Additional Reliability Data:	Contact your local onse	Contact your local onsemi Sales Office or <u>c.l.yang@lps.com.cn</u>		
Type of Notification:	days prior to implement onsemi will consider the	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com		
Marking of Parts/ Traceability of Change:	existing Leshan facility	At the expiration of this PCN devices will be assembled with 0.8 mils PD-coated Cu wire at onsemi existing Leshan facility. Products assembled with 0.8 mils PD-coated Cu wire from the onsemi facility will have a Finish Goods Date Code of WW15 2022 or greater.		
Change Category:	Wafer Fab Change, As	Wafer Fab Change, Assembly Change		
Change Sub-Category(s):	Material Change	Material Change		
Sites Affected:				
onsemi Sites		External Foundry/Subcon Sites		
Leshan Phoenix Semiconductor, China		None		
onsemi Roznov, Czech Republic				
Description and Purpose:		·		

Description and Purpose:

onsemi is notifying customers of its use of 0.8 mils Pd-coated Cu wire for JFET devices assembled in SOT-23 at onsemi Leshan, China facility. The change requires wafer top metal thickness increase from 15 KÅ AlSi to 20 KÅ AlSi. Upon the expiration of this PCN, these devices will be built with 0.8 mils Pd-coated Cu wire and will use the thicker top at the same site. Datasheet specifications and product electrical performance remain unchanged. Reliability Qualification and full electrical characterization over temperature has been performed.

Before Change Description		After Change Description	
Bond Wire	0.8 mils Au wire	0.8 mils PD-coated Cu wire	
Wafer top metal	15KA AlSi	20KA AlSi	

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Reliability Data Summary:

QV DEVICE NAME : SMMBFJ177LT1G RMS: 79236

PACKAGE: SOT23

PACKAGE. JUI	25			
Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs	0/231
HTGB	JESD22-A108	Ta=150°C, 100% max rated Vgss	1008 hrs	0/231
HTSL	JESD22-A103	Ta=150°C	2016 hrs	0/231
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	30К сус	0/231
TC	JESD22-A104	Ta= -65°C to +150°C	2000 сус	0/231
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hrs	0/231
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C	-	-
RSH	JESD22- B106	Ta = 265C, 10 sec	-	0/30
SD	JSTD002	Ta = 245C, 5 sec	-	0/30

QV DEVICE NAME : SMMBF4393LT1G

RMS: 79238

PACKAGE: SUI	23			
Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs	0/77
HTGB	JESD22-A108	Ta=150°C, 100% max rated Vgss	1008 hrs	0/77
HTSL	JESD22-A103	Ta=150°C	2016 hrs	0/77
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	30К сус	0/77
TC	JESD22-A104	Ta= -65°C to +150°C	2000 сус	0/77
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hrs	0/77
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/77
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C	-	-
RSH	JESD22- B106	Ta = 265C, 10 sec	-	0/30
SD	JSTD002	Ta = 245C, 5 sec	-	0/10

Electrical Characteristics Summary:

Full characterization and ESD performance meet datasheet specification. Detail of electrical characterization result is available upon request.

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle	
MMBFJ175LT3G	SMMBFJ175LT1G	



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MMBF4393LT3G	SMMBF4393LT1G
MMBFJ310LT3G	SMMBF4393LT1G
MMBFU310LT1G	SMMBF4393LT1G
MMBFJ175LT1G	SMMBFJ175LT1G
MMBFJ309LT1G	SMMBF4393LT1G
MMBF4391LT1G	SMMBF4393LT1G
MMBF4393LT1G	SMMBF4393LT1G
MMBF4392LT1G	SMMBF4393LT1G
MMBFJ177LT1G	SMMBFJ175LT1G
MMBFJ310LT1G	SMMBF4393LT1G

Appendix A: Changed Products

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Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
MMBFJ175LT3G		SMMBFJ175LT1G		
MMBFJ310LT3G		SMMBF4393LT1G		
MMBFU310LT1G		SMMBF4393LT1G		
MMBFJ175LT1G		SMMBFJ175LT1G		
MMBFJ309LT1G		SMMBF4393LT1G		
MMBF4391LT1G		SMMBF4393LT1G		
MMBF4393LT1G		SMMBF4393LT1G		
MMBF4392LT1G		SMMBF4393LT1G		
MMBFJ177LT1G		SMMBFJ175LT1G		
MMBFJ310LT1G		SMMBF4393LT1G		
MMBF4393LT3G		SMMBF4393LT1G		